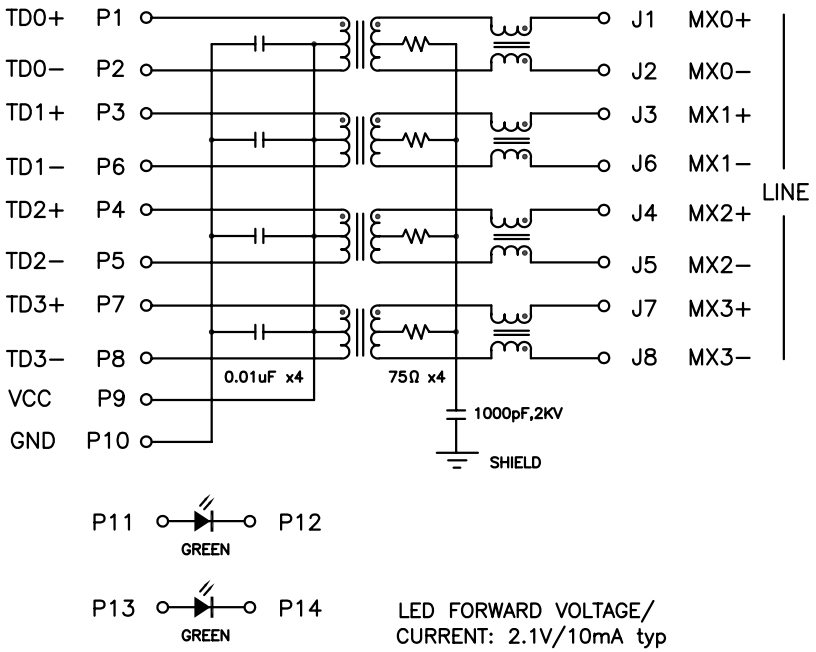
PRELIMINARY

PART NO. : HFJT1-1G04-L11RL

FASTJACK™ (TABUP) WITH 1000BASE-T MAGNETICS
DESIGNED FOR IEEE802.3ab GIGABIT APPLICATIONS
LEAD-FREE/RoHS COMPLIANT
COMPATIBLE TO LEAD-FREE WAVE SOLDERING PROCESS FOR THROUGH HOLE COMPONENTS
OPERATING TEMPERATURE 0/70°C

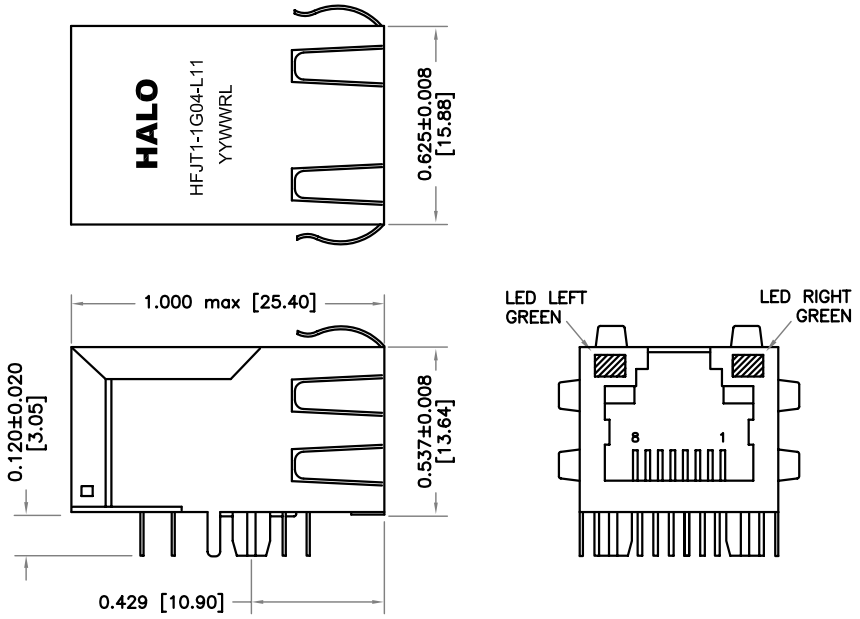
ELECTRICAL SPECIFICATIONS @ 25° C

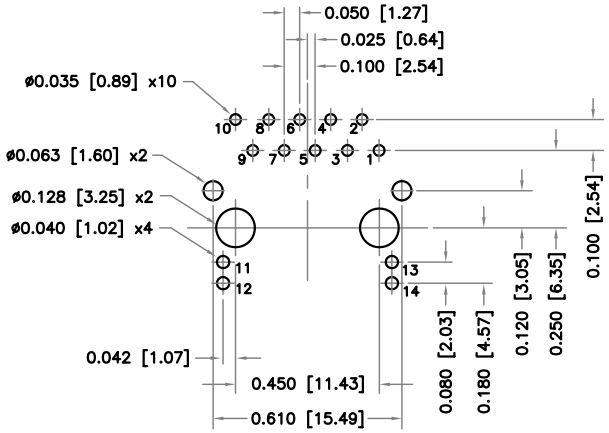
TURNS RATIO	1:1 ±3%
OCL (100KHz,0.1V,8mA)	350µH min
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK 1-100MHz	-35dB typ
CMR 0.1-30MHz	-50dB typ
30-60MHz	-40dB typ
60-100MHz	-35dB typ
ISOLATION	1,500Vrms



HALO/PBL	TITLE	FastJack™ SINGLE		SIGNATURES	DATE	REV.	DESC.	DATE
	FOR	GIGABIT ETHERNET		DRAWN PETER LU	8/8/05	B	UPDATE SCHEMATIC	8/17/05
	PART NO.	HFJT1-1G04-L11RL		CHECKED				
	SCALE	NONE	PAGE 1 OF 2	APPROVED				
CALIFORNIA, USA KOWLOON, HONG KONG SINGAPORE				FILE HFJT1-1G04-L11RL.DWG				

PRELIMINARY





RECOMMENDED P.C. BOARD PATTERN (COMP. SIDE)

Housing Material: Polyester, Black UL94V-0
Contacts: Phosphor Bronze 30µin Au plating over Ni
Leads: Matte Sn plating
Shield: Cu Alloy with Ni plating 40µin min
Durability: 1000 mating cycles
Dimensions: Inch [mm]
Tolerances: ±0.008 inch if not specified

HALO/PBL	TITLE	FastJack™ SINGLE		SIGNATURES	DATE	REV.	DESC.	DATE
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	PART NO.	HFJT1-1G04-L11RL		CHECKED				
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